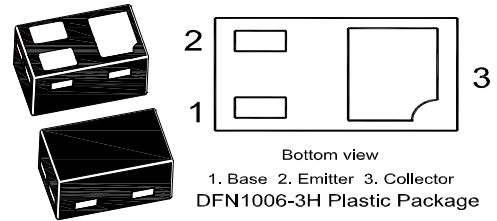


BC846P...BC850P

NPN Silicon Epitaxial Transistor

for switching and amplifier applications



Absolute Maximum Ratings ($T_a = 25^\circ\text{C}$)

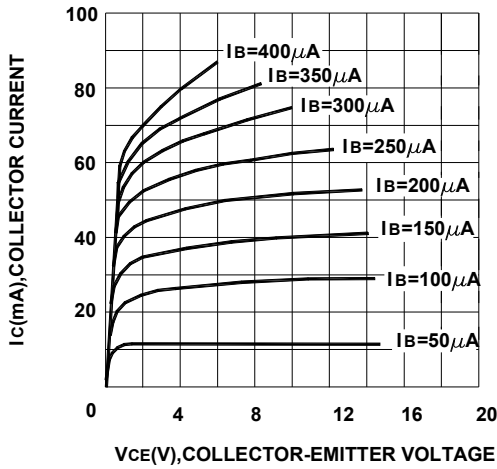
Parameter	Symbol	Value	Unit	
Collector Base Voltage	BC846P	V_{CBO}	80	V
	BC847P, BC850P	V_{CBO}	50	V
	BC848P, BC849P	V_{CBO}	30	V
Collector Emitter Voltage	BC846P	V_{CEO}	65	V
	BC847P, BC850P	V_{CEO}	45	V
	BC848P, BC849P	V_{CEO}	30	V
Emitter Base Voltage	BC846P, BC847P	V_{EBO}	6	V
	BC848P, BC849P, BC850P	V_{EBO}	5	V
Collector Current	I_C	100	mA	
Peak Collector Current	I_{CM}	200	mA	
Power Dissipation	P_{tot}	150	mW	
Junction Temperature	T_j	150	$^\circ\text{C}$	
Storage Temperature Range	T_{stg}	- 65 to + 150	$^\circ\text{C}$	

Characteristics at $T_a = 25^\circ\text{C}$

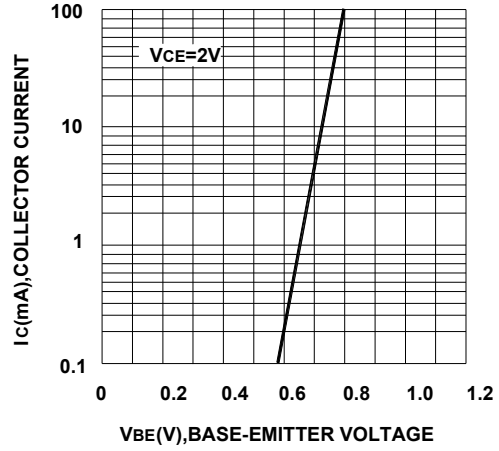
Parameter	Symbol	Min.	Typ.	Max.	Unit	
DC Current Gain at $V_{CE} = 5\text{ V}$, $I_C = 2\text{ mA}$	Current Gain Group A	h_{FE}	110	-	220	-
	B	h_{FE}	200	-	450	-
	C	h_{FE}	420	-	800	-
Collector Base Cutoff Current at $V_{CB} = 30\text{ V}$	I_{CBO}	-	-	15	nA	
Collector Emitter Saturation Voltage at $I_C = 10\text{ mA}$, $I_B = 0.5\text{ mA}$ at $I_C = 100\text{ mA}$, $I_B = 5\text{ mA}$	V_{CEsat}	-	-	250	mV	
	V_{CEsat}	-	-	600	mV	
Base Emitter On Voltage at $V_{CE} = 5\text{ V}$, $I_C = 2\text{ mA}$ at $V_{CE} = 5\text{ V}$, $I_C = 10\text{ mA}$	$V_{BE(on)}$	580	-	700	mV	
	$V_{BE(on)}$	-	-	720	mV	
Transition Frequency at $V_{CE} = 5\text{ V}$, $I_C = 10\text{ mA}$, $f = 100\text{ MHz}$	f_T	-	300	-	MHz	
Output Capacitance at $V_{CB} = 10\text{ V}$, $f = 1\text{ MHz}$	C_{ob}	-	-	6	pF	
Input Capacitance at $V_{EB} = 0.5\text{ V}$, $f = 1\text{ MHz}$	C_{ib}	-	9	-	pF	

TOP DYNAMIC

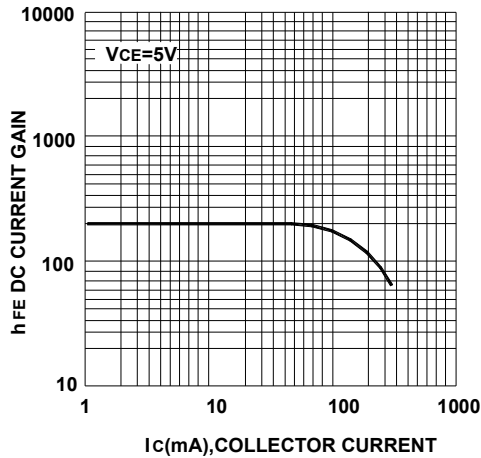
STATIC CHARACTERISTIC



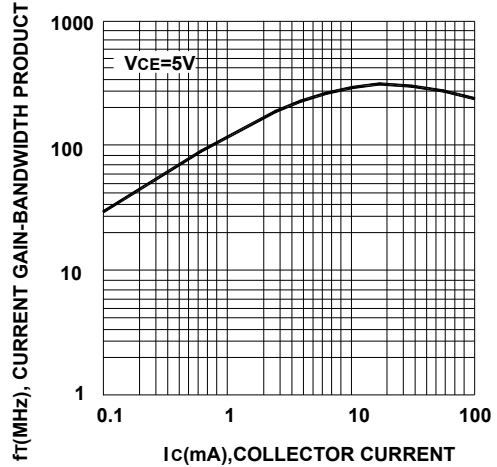
BASE-EMITTER ON VOLTAGE



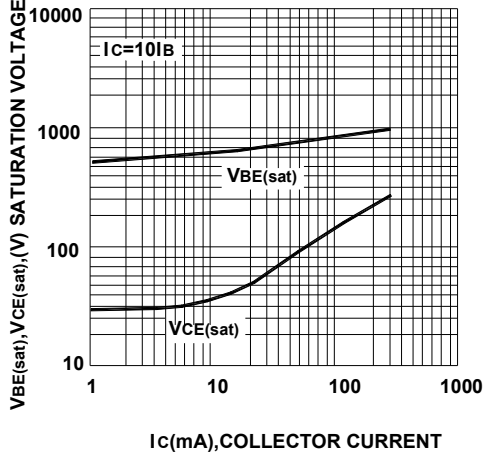
DC CURRENT GAIN



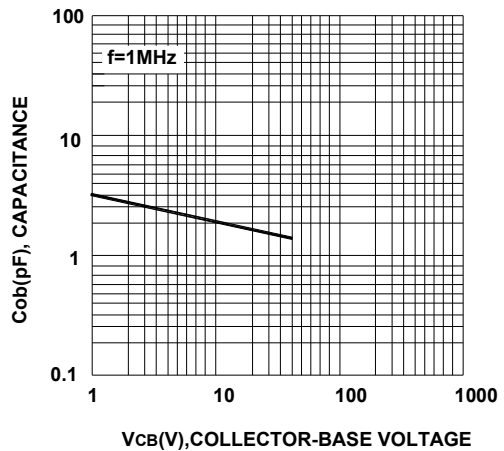
CURRENT GAIN BANDWIDTH PRODUCT



BASE-EMITTER SATURATION VOLTAGE
COLLECTOR-EMITTER SATURATION VOLTAGE



COLLECTOR OUTPUT CAPACITANCE

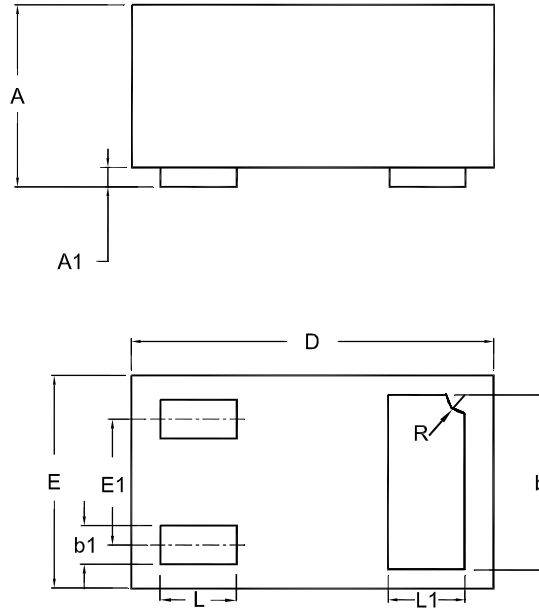


BC846P...BC850P

PACKAGE OUTLINE

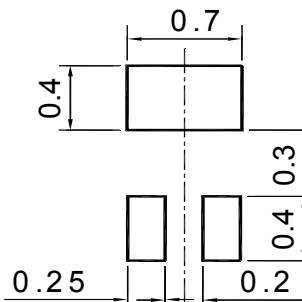
Plastic surface mounted package

DFN1006-3H



UNIT	A	A1	b	b1	D	E	E1	L	L1	R
mm	0.51	0.05	0.55	0.2	1.05	0.65	0.325	0.3	0.3	0.15
	0.46	0	0.45	0.1	0.95	0.55		0.2	0.2	0.05

Recommended Soldering Footprint



Packing information

Package	Tape Width (mm)	Pitch		Reel Size		Per Reel Packing Quantity
		mm	inch	mm	inch	
DFN1006-3H	8	4 ± 0.1	0.157 ± 0.004	178	7	5,000

TOP DYNAMIC